

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"ru.sub.o.sub.2"	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/20 10:52
L2	3	"ru.sub.2 o.sub.2"	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/20 10:52
L3	4082	"ruo.sub.2"	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/20 10:53
L4	1275	"ruo.sub.2" with 'ru'	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/20 10:55
L5	141	"ruo.sub.2" with (barier diffusion)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/20 10:56
L6	251	"ruo.sub.2" with (barrier diffusion)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/20 10:58
L7	14	"ruo.sub.2" with ((barrier diffusion) with (copper 'cu'))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/20 17:21
L8	22	("ruo.sub.2" ruthenium adj oxide) with ((barrier diffusion) with (copper 'cu'))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/20 13:26
L9	12	("ruo.sub.2" ruthenium adj oxide) with ((barrier diffusion) with interconnect\$3)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/20 14:30
L10	235	("ru" ruthenium) with ((barrier diffusion) with (copper 'cu'))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/20 14:31

L11	47	("re" ruthenium) near5 ((barrier diffusion) with (copper 'cu'))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/20 15:27
L12	4	(("ru" ruthenium) near5 ("ruo.sub.2" ruthenium near3 oxide) near5 (barrier diffusion) with (copper 'cu'))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/20 15:35
L13	8212	(("ru" ruthenium) ("ruo.sub.2" ruthenium near3 oxide)) near5 (copper 'cu')	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/20 15:36
L14	362	( ("ruo.sub.2" ruthenium near3 oxide)) near5 (copper 'cu')	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/20 15:36
L15	8118	("ru" ruthenium) near5 (copper 'cu')	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/20 15:36
L16	268	14 and 15	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/20 15:37
L17	1	"5555486".PN.	USPAT; USOCR	OR	ON	2005/06/20 16:44
L18	22	(("ruo.sub.2" ruthenium adj oxide) with (barrier diffusion)) with (copper 'cu')	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/06/20 17:22
S22	1794	(dielectric near5 inter adj layer)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/02 17:50
S24	247	(diffusion near3 (layer barrier)) with (('ru' rhthenium) (rhthenium near3 oxide ))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/02 18:06
S25	0	S22 with S24	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/02 17:53

S26	3	S22 and S24	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/02 17:53
S27	164	S24 and dielectric	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/02 17:58
S28	37	S27 and copper	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/02 17:58
S29	8588	(copper 'cu') with (('ru' rhthenium) (rhthenium near3 oxide ))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/02 18:06
S30	71	(copper 'cu') with (('ru' rhthenium) (rhthenium near3 oxide )) with dielectric	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/02 18:07
S31	114	(copper 'cu') with (('ru' rhthenium) (rhthenium near3 oxide )) with barrier	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/03 05:44
S32	14	(copper 'cu') with (('ru' rhthenium) (rhthenium near3 oxide )) with barrier with dielectric	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/02 18:19
S33	1	10/916257	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/02 18:19
S34	807	('ru' rhthenium rhthenium near3 oxide ruo\$6) with barrier	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/03 05:56
S35	356	S34 and ((etch\$3 pattern\$3) with (dielectric 'ild' inter adj layer interlayer))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/03 05:56
S36	313	S35 and ((etch\$3 pattern\$3) with (trench hole via opening groove damascene dual adj damascene))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/03 05:57

S37	75	S36 and ('cu' copper) with (trench hole via opening groove damascene dual adj damascene))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/03 06:02
S38	58	S37 and (interconnect\$3 inter adj connect\$3)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/03 06:00
S39	1167	('ru' ruthenium ruthenium near3 oxide ruo\$6) with barrier	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/03 05:57
S40	509	S39 and ((etch\$3 pattern\$3) with (dielectric 'ild' inter adj layer interlayer))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/03 05:59
S41	445	S40 and ((etch\$3 pattern\$3) with (trench hole via opening groove damascene dual adj damascene))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/03 05:59
S42	13348	('ru' ruthenium ruthenium near3 oxide ruo\$6) with (barrier liner seed lining film layer)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/03 06:07
S43	3744	S42 and ((etch\$3 pattern\$3) with (dielectric 'ild' inter adj layer interlayer insulat\$3))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/03 05:59
S44	2631	S43 and ((etch\$3 pattern\$3) with (trench hole via opening groove damascene dual adj damascene))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/03 06:00
S45	874	S44 and (interconnect\$3 inter adj connect\$3 metalization)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/03 06:01
S46	271	S45 and ('cu' copper) with (trench hole via opening groove damascene dual adj damascene))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/03 06:02
S47	170	S46 and diffusion near4 (barrier layer film liner)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/03 06:03

S48	170	S47 and ('ru' ruthenium ruthenium near3 oxide ruo\$6 'cu' copper)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/03 09:29
S49	3	"6664186"	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/03 07:47
S50	1	"6346484".PN.	USPAT; USOCR	OR	ON	2005/02/03 08:59
S51	1	"20020064592".PN.	US-PGPU B	OR	ON	2005/02/03 09:17
S52	1	"20020064592".PN.	US-PGPU B	OR	ON	2005/02/03 09:17
S53	1	"20020036309".PN.	US-PGPU B	OR	ON	2005/02/03 09:17
S54	1	"6482740".PN.	USPAT; USOCR	OR	ON	2005/02/03 09:17
S55	1	"6482740".PN.	USPAT; USOCR	OR	ON	2005/02/03 09:17
S56	1	"6472322".PN.	USPAT; USOCR	OR	ON	2005/02/03 09:22
S57	1	"6472322".PN.	USPAT; USOCR	OR	ON	2005/02/03 09:22
S58	1	"6433379".PN.	USPAT; USOCR	OR	ON	2005/02/03 09:23
S59	1	"6368910".PN.	USPAT; USOCR	OR	ON	2005/02/03 09:23
S60	1	"6368910".PN.	USPAT; USOCR	OR	ON	2005/02/03 09:25
S61	1	"6335241".PN.	USPAT; USOCR	OR	ON	2005/02/03 09:25
S62	1	10/600039	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/03 13:29
S63	0	2003/0003658	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/03 13:29

S64	1	"20030003658"	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/03 13:33
S65	6	"6255205"	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/02/03 13:34